# **Hex D Flip-Flop**

The LSTTL/MSI SN74LS174 is a high speed Hex D Flip-Flop. The device is used primarily as a 6-bit edge-triggered storage register. The information on the D inputs is transferred to storage during the LOW to HIGH clock transition. The device has a Master Reset to simultaneously clear all flip-flops. The LS174 is fabricated with the Schottky barrier diode process for high speed and is completely compatible with all ON Semiconductor TTL families.

- Edge-Triggered D-Type Inputs
- Buffered-Positive Edge-Triggered Clock
- Asynchronous Common Reset
- Input Clamp Diodes Limit High Speed Termination Effects

#### **GUARANTEED OPERATING RANGES**

Symbol	Parameter	Min	Тур	Max	Unit
V <sub>CC</sub>	Supply Voltage	4.75	5.0	5.25	V
T <sub>A</sub>	Operating Ambient Temperature Range		25	70	°C
I <sub>OH</sub>	H Output Current – High			-0.4	mA
I <sub>OL</sub>	Output Current – Low			8.0	mA



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> LOW POWER SCHOTTKY



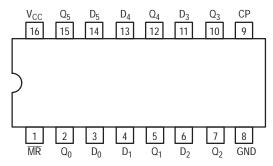




#### **ORDERING INFORMATION**

Device	Package	Shipping
SN74LS174N 16 Pin DIP		2000 Units/Box
SN74LS174D	16 Pin	2500/Tape & Reel

#### CONNECTION DIAGRAM DIP (TOP VIEW)



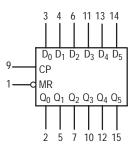
NOTE: The Flatpak version has the same pinouts (Connection Diagram) as the Dual In-Line Package.

		LOADING (Note a)	
PIN NAMES		HIGH	LOW
$D_0 - D_5$ $CP$ $\overline{MR}$ $Q_0 - Q_5$	Data Inputs Clock (Active HIGH Going Edge) Input Master Reset (Active LOW) Input Outputs	0.5 U.L. 0.5 U.L. 0.5 U.L. 10 U.L.	0.25 U.L. 0.25 U.L. 0.25 U.L. 5 U.L.

NOTES:

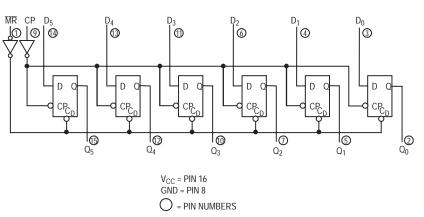
a) 1 TTL Unit Load (U.L.) = 40 µA HIGH/1.6 mA LOW.

LOGIC SYMBOL



V<sub>CC</sub> = PIN 16 GND = PIN 8

LOGIC DIAGRAM



### FUNCTIONAL DESCRIPTION

The LS174 consists of six edge-triggered D flip-flops with individual D inputs and Q outputs. The Clock (CP) and Master Reset ( $\overline{MR}$ ) are common to all flip-flops.

Each D input's state is transferred to the corresponding flip-flop's output following the LOW to HIGH Clock (CP) transition.

A LOW input to the Master Reset ( $\overline{\text{MR}}$ ) will force all outputs LOW independent of Clock or Data inputs. The LS174 is useful for applications where the true output only is required and the Clock and Master Reset are common to all storage elements.

#### TRUTH TABLE

Inputs (t = n, MR = H)	Outputs (t = n+1) Note 1
D	Q
Н	Н
L	L

Note 1: t = n + 1 indicates conditions after next clock.

#### DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

		Limits					
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions	
V <sub>IH</sub>	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs	
V <sub>IL</sub>	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs	
V <sub>IK</sub>	Input Clamp Diode Voltage		-0.65	-1.5	V	$V_{CC} = MIN, I_{IN} = -18 \text{ mA}$	
V <sub>OH</sub>	Output HIGH Voltage	2.7	3.5		V	$V_{CC}$ = MIN, I <sub>OH</sub> = MAX, V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> per Truth Table	
			0.25	0.4	V	I <sub>OL</sub> = 4.0 mA	$V_{CC} = V_{CC} MIN,$
V <sub>OL</sub>	Output LOW Voltage		0.35	0.5	V	I <sub>OL</sub> = 8.0 mA	V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> per Truth Table
				20	μΑ	$V_{CC} = MAX, V_{IN}$	= 2.7 V
lн	Input HIGH Current			0.1	mA	V <sub>CC</sub> = MAX, V <sub>IN</sub> = 7.0 V	
I <sub>IL</sub>	Input LOW Current			-0.4	mA	$V_{CC} = MAX, V_{IN} = 0.4 V$	
I <sub>OS</sub>	Short Circuit Current (Note 1)	-20		-100	mA	V <sub>CC</sub> = MAX	
I <sub>CC</sub>	Power Supply Current			26	mA	V <sub>CC</sub> = MAX	

Note 1: Not more than one output should be shorted at a time, nor for more than 1 second.

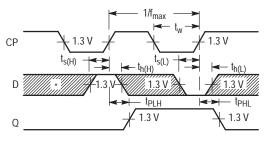
#### **AC CHARACTERISTICS** ( $T_A = 25^{\circ}C$ )

		Limits				
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
f <sub>MAX</sub>	Maximum Input Clock Frequency	30	40		MHz	
t <sub>PHL</sub>	Propagation Delay, MR to Output		23	35	ns	V <sub>CC</sub> = 5.0 V C <sub>L</sub> = 15 pF
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay, Clock to Output		20 21	30 30	ns	

#### AC SETUP REQUIREMENTS (T<sub>A</sub> = 25°C)

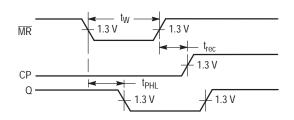
		Limits				
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
t <sub>W</sub>	Clock or MR Pulse Width	20			ns	
ts	Data Setup Time	20			ns	V = 5 0 V
t <sub>h</sub>	Data Hold Time	5.0			ns	V <sub>CC</sub> = 5.0 V
t <sub>rec</sub>	Recovery Time	25			ns	

#### AC WAVEFORMS



\*The shaded areas indicate when the input is permitted to change for predictable output performance.





#### Figure 2. Master Reset to Output Delay, Master Reset Pulse Width, and Master Reset Recovery Time

#### **DEFINITIONS OF TERMS**

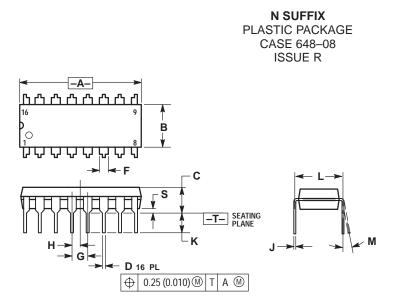
SETUP TIME  $(t_s)$  — is defined as the minimum time required for the correct logic level to be present at the logic input prior to the clock transition from LOW to HIGH in order to be recognized and transferred to the outputs.

HOLD TIME  $(t_h)$  — is defined as the minimum time following the clock transition from LOW to HIGH that the logic level must be maintained at the input in order to ensure

continued recognition. A negative HOLD TIME indicates that the correct logic level may be released prior to the clock transition from LOW to HIGH and still be recognized.

RECOVERY TIME  $(t_{rec})$  — is defined as the minimum time required between the end of the reset pulse and the clock transition from LOW to HIGH in order to recognize and transfer HIGH Data to the Q outputs.

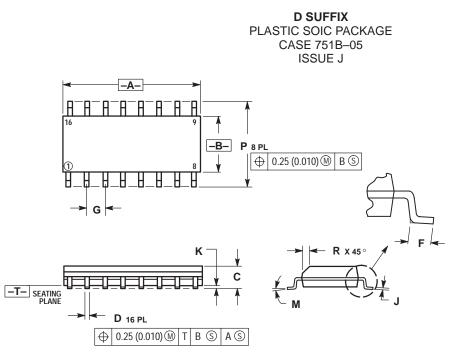
### PACKAGE DIMENSIONS



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL. 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH. 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	ETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
К	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
Μ	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

## PACKAGE DIMENSIONS



NOTES:

- NOTES:
   DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: MILLIMETER.
   DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
   MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
   DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
   PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	INCHES		
DIM	MIN	MAX	MIN	MAX		
Α	9.80	10.00	0.386	0.393		
В	3.80	4.00	0.150	0.157		
С	1.35	1.75	0.054	0.068		
D	0.35	0.49	0.014	0.019		
F	0.40	1.25	0.016	0.049		
G	1.27	BSC	0.050	) BSC		
J	0.19	0.25	0.008	0.009		
К	0.10	0.25	0.004	0.009		
M	0 °	7°	0 °	7°		
Р	5.80	6.20	0.229	0.244		
R	0.25	0.50	0.010	0.019		

## **Notes**

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